

RFM products are now Murata products.

- Steep Roll-off SAW Filter for 869.00 MHz Unlicensed Band
- Complies with Directive 2002/95/EC (RoHS)
- No Matching Required for Operation in 50 Ω Environment

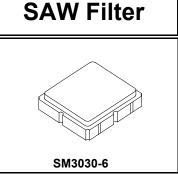


Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	14	dBm
DC Voltage on any Non-ground Terminal	5	V
Operating Temperature Range	-30 to +65	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Soldering Profile Maximum Temperature, 5 cycles/10 s maximum	265	°C

869.00 MHz

SF2137E-1



3000 Pieces/Reel

Electrical Characteristics

Characteristic	Sym	Notes	Min	Тур	Max	Units
Center Frequency	f _C			869.00		MHz
Insertion Loss, 868 to 870 MHz	IL			2.7	3.5	dB
Amplitude Ripple, 868 to 870 MHz				0.2	1.5	dB _{P-P}
Attenuation Referenced to 0 dB:						
DC to 828 MHz	-		45	51		
828 to 849 MHz	-		30	40		
881 to 890 MHz	-		10	18		-10
890 to 925 MHz	-		22	38		dB
925 to 1200 MHz	-		40	49		
1200 to 1740 MHz			36	49		
Source Impedance	Z _S			50		Ω
Load Impedance	ZL			50		Ω
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization, Y=year, WW=week, S=shift, Dot=pin 1 indicator	994, YWWS					
Standard Reel Quantity Reel Size 7 Inch	500 Pieces/Reel					

Electrical Connections

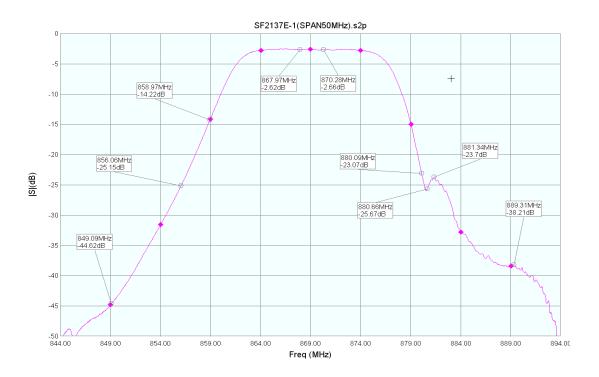
Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

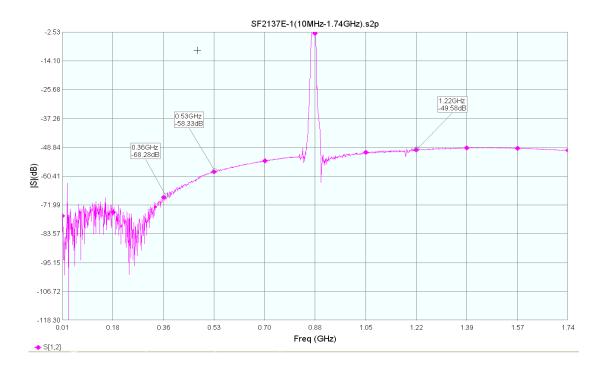
Reel Size 13 Inch

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

- 1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance
- 2
- Unless noted otherwise, all specifications apply over the operating temperating temperati 3.
- 4. The design, manufacturing process, and specifications of this filter are subject to change.
- 5 US and international patents may apply.
- Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd. 6.

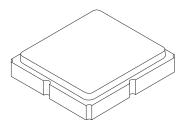


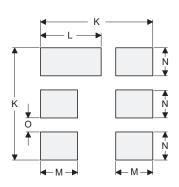


SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint

Case and PCB Footprint Dimensions





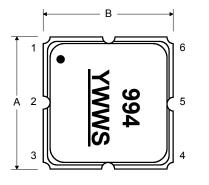
PCB Footprint Top View

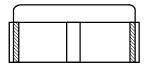
Dimension		mm		Inches		
Dimension	Min	Nom	Max	Min	Nom	Max
Α	2.87	3.00	3.13	0.113	0.118	0.123
В	2.87	3.00	3.13	0.113	0.118	0.123
С	1.12	1.25	1.40	0.044	0.049	0.055
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
Н	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
к		3.20			0.126	
L		1.70			0.067	
М		1.05			0.041	
N		0.81			0.032	
0		0.38			0.015	

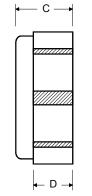
Case Materials

Materials				
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al ₂ O ₃ Ceramic			
Pb Free				

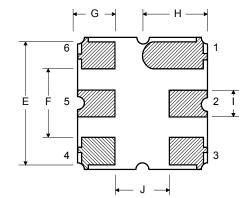
Top View



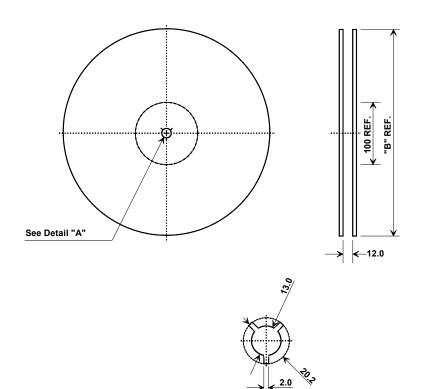




Bottom View



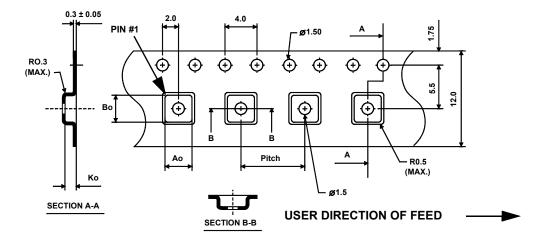
Tape and Reel Specifications



	"B"	Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions					
Ao	3.35 mm				
Во	3.35 mm				
Ко	1.40 mm				
Pitch	8.0 mm				
W	12.0 mm				



Typical Solder Reflow Profile

